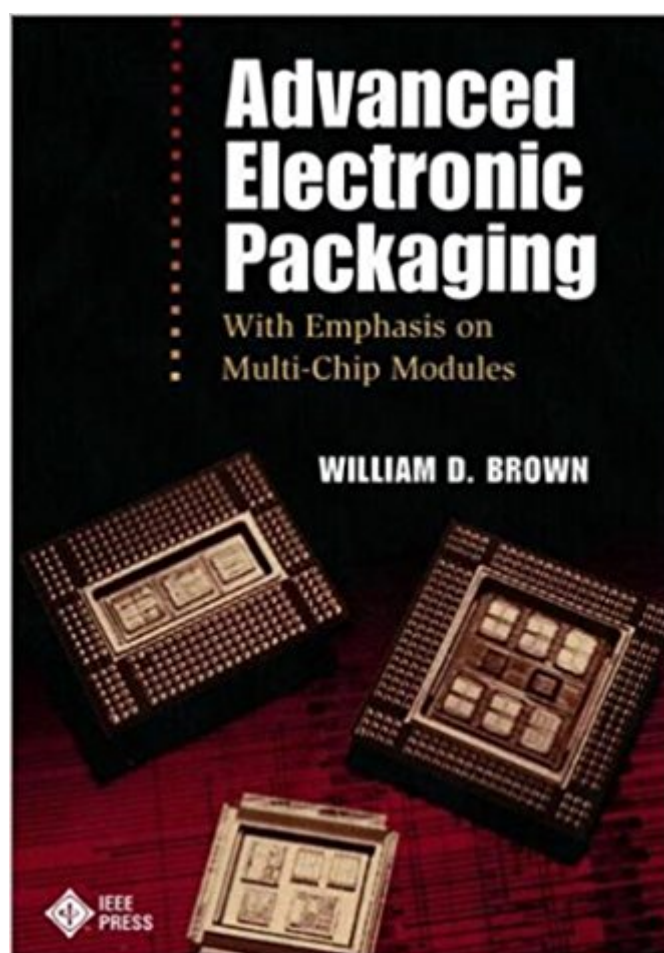


The book was found

Advanced Electronic Packaging: With Emphasis On Multichip Modules (IEEE Press Series On Microelectronic Systems)



Synopsis

Packaging is rapidly becoming an area of microelectronics technology which can limit the operating speed on an integrated circuit. To address this concern, much research and development attention now focuses on packaging in an effort to prevent it from impeding the speed of electronic systems. With *Advanced Electronic Packaging*, readers can learn about the full range of packaging concepts, from the introductory to the advanced level, and gain a deeper understanding of this rapidly growing area of microelectronics. As an excellent desk reference for practicing engineers or as an ideal text for students in interdisciplinary engineering classes, this comprehensive book discusses all aspects of the sciences and technologies involved in the fabrication, testing, reliability, and packaging of integrated circuits, specifically, multichip modules (MCM). In addition, you will find industrial case studies for several MCM technologies along with an assessment of design tradeoffs. Also addressed are the critical role of economics and future trends in electronic packaging. An Instructor's Manual presenting detailed solutions to all the problems in the book is available upon request from the Wiley Marketing Department.

Book Information

Series: IEEE Press Series on Microelectronic Systems (Book 1)

Hardcover: 784 pages

Publisher: Wiley-IEEE Press; 1 edition (October 27, 1998)

Language: English

ISBN-10: 0780347005

ISBN-13: 978-0780347007

Product Dimensions: 7.2 x 1.9 x 10.2 inches

Shipping Weight: 3.5 pounds

Average Customer Review: 5.0 out of 5 stars [See all reviews](#) (1 customer review)

Best Sellers Rank: #671,764 in Books (See Top 100 in Books) #32 in [Books > Engineering & Transportation > Engineering > Industrial, Manufacturing & Operational Systems > Industrial Design > Packaging](#) #95 in [Books > Engineering & Transportation > Engineering > Electrical & Electronics > Circuits > Integrated](#) #198 in [Books > Engineering & Transportation > Engineering > Electrical & Electronics > Electronics > Microelectronics](#)

Customer Reviews

I am a student of Dr. Brown. I must emphasize that the book that he has edited and a part of which he has written, is just excellent in its quality and quantity. By quality I mean its the best book on

packaging that I have read and by quantity I mean the book has something on everything. Most of the books are like a lot on a topic and very less on most of the other topics, but this book surpasses everything. It treats every chapter fairly and equally. The book will not make one an expert in packaging, but would surely make one feel satisfied with the content and knowledge. I hope that other readers too would find this book good and informative.

[Download to continue reading...](#)

Advanced Electronic Packaging: With Emphasis on Multichip Modules (IEEE Press Series on Microelectronic Systems) IEEE Std 1100-1999, IEEE Recommended Practice for Powering and Grounding Electronic Equipment (The IEEE Emerald Book) Low-Voltage/Low-Power Integrated Circuits and Systems: Low-Voltage Mixed-Signal Circuits (IEEE Press Series on Microelectronic Systems) CMOS Circuit Design, Layout, and Simulation, 3rd Edition (IEEE Press Series on Microelectronic Systems) High-Performance System Design: Circuits and Logic (IEEE Press Series on Microelectronic Systems) IEEE Recommended Practice for Grounding of Industrial and Commercial Power Systems (IEEE Green Book) Power Conversion and Control of Wind Energy Systems (IEEE Press Series on Power Engineering) Food Packaging Science and Technology (Packaging and Converting Technology) Performance Evaluation and High Speed Switching Fabrics and Networks: ATM, Broadband ISDN, and MAN Technology (A Selected Reprint Volume) (IEEE Press Selected Reprint Series) Key Papers in the Development of Coding Theory (IEEE Press Selected Reprint Series) Embedded Systems Building Blocks: Complete and Ready-to-Use Modules in C++ (Packaging and Converting Technology) Constellation Shaping, Nonlinear Precoding, and Trellis Coding for Voiceband Telephone Channel Modems: with Emphasis on ITU-T Recommendation V.34 (The ... Series in Engineering and Computer Science) Circuits, Interconnections, and Packaging for VLSI (Addison-Wesley VLSI systems series) Vegetable Insect Management: With Emphasis on the Midwest Nonvolatile Memory Technologies with Emphasis on Flash: A Comprehensive Guide to Understanding and Using Flash Memory Devices Functional mammalian neuroanatomy,: With emphasis on dog and cat, including an atlas of dog central nervous system The management of pain,: With special emphasis on the use of analgesic block in diagnosis, prognosis, and therapy Advanced MEMS Packaging Microelectronic Circuits (The Oxford Series in Electrical and Computer Engineering) 7th edition

[Dmca](#)